Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	6 X 6 X 0.75 (3.7 EP)
Lead Count	36
Terminal Finish	100 Sn
MS Number	MS011014C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.27E-02	86.91	869100	32.72	327239
Thermosets	Epoxy & Phenol Resin	Proprietary	4.81E-03	12.78	127800	4.81	48120
Other inorganic materials	Carbon black	1333-86-4	1.17E-04	0.31	3100	0.12	1167
Subtotal			3.76 E-02	100.00	1000000	37.65	376526

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.03 E-02	97.50	975000	50.34	503402
Copper & its alloys	Iron	7439-89-6	1.21 E-03	2.35	23500	1.21	12133
Copper & its alloys	Zinc	7440-66-6	6.19 E-05	0.12	1200	0.06	620
Copper & its alloys	Phosphorus	7723-14-0	1.55 E-05	0.03	300	0.02	155
Subtotal			5.16 E-02	100.00	1000000	51.63	516310

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.20 E-04	100.0	1000000	0.62	6204

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.68 E-03	100.0	1000000	1.68	16810

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.84 E-03	99.00	990000	1.84	18425
Precious metals	Palladium	7440-05-3	1.86 E-05	1.00	10000	0.02	186
Subtotal			1.86 E-03	100.0	1000000	1.86	18611

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.40 E-03	100.0	1000000	5.40	54032

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.46 E-04	73.54	735400	0.85	8462
Other organic materials	Epoxy resin A	TS ref# 10013	8.45 E-05	7.35	73500	0.08	846
Others	Anhydride	TS ref# 10181	8.45 E-05	7.35	73500	0.08	846
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.38 E-05	2.94	29400	0.03	338
Other organic materials	Epoxy resin B	TS ref# 10237	3.38 E-05	2.94	29400	0.03	338
Others	Epoxy resin modifier	TS ref# 10038	3.38 E-05	2.94	29400	0.03	338
Others	Anhydride	TS ref# 10180	3.38 E-05	2.94	29400	0.03	338
Subtotal			1.15 E-03	100.0	1000000	1.15	11507

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.99 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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